



W83194BR-648

Data Sheet

WIBOND

CLOCK GENERATOR

FOR

SIS P4 SERIES CHIPSET

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1. GENERAL DESCRIPTION

The W83194BR-648 is a Clock Synthesizer for SIS P4 series chipset. W83194BR-648 provides all clocks required for high-speed Intel Pentium 4, and also provides 32 different frequencies of CPU clocks frequency setting. All clocks are externally selectable with smooth transitions. The W83194BR-648 makes SDRAM in synchronous or asynchronous frequency with CPU clocks.

The W83194BR-648 provides step-less frequency programming by controlling the VCO freq. and the programmable AGP, PCI clock output divisor ratio. AGP and PCI frequency can be fixed to be four kinds of different frequency outputs. A watchdog timer is quipped and when time out, register9 bit5 will be set to 1 for warning. Spread spectrum built in at $\pm 0.5\%$ or $\pm 0.25\%$ to reduce EMI. Programmable stopping individual clock outputs and frequency selection through I²C interface.

The W83194BR-648 accepts a 14.318 MHz reference crystal as its input and runs on a 3.3V supply. High drive PCI CLOCK outputs typically provide greater than 1V /nS slew rate into 30 pF loads. The fixed frequency outputs as REF, 24 MHz, and 48 MHz provide better than 0.5V /nS slew rate.

2. FEATURES

- Supports Intel Pentium 4 CPU with I²C.
- 2 pairs of differential CPU clocks
- 2 ZCLK for SIS chipsets
- 2 AGP clocks
- 1 SDRAM output clock for chipset
- 8 PCI synchronous clocks
- 1 24/48 MHz, 1 48 MHz
- 3 REF clocks
- Skew --- CPU to SDRAM < 1 ns, PCI to PCI < 500ps, AGP to AGP < 175ps
- Smooth frequency switch with selections from 66 to 200 MHz
- I²C 2-Wire serial interface and I²C read back
- Flexible spread spectrum to reduce EMI
- Programmable registers to enable/stop each output
- Packaged in 48-pin SSOP

3. PIN CONFIGURATION

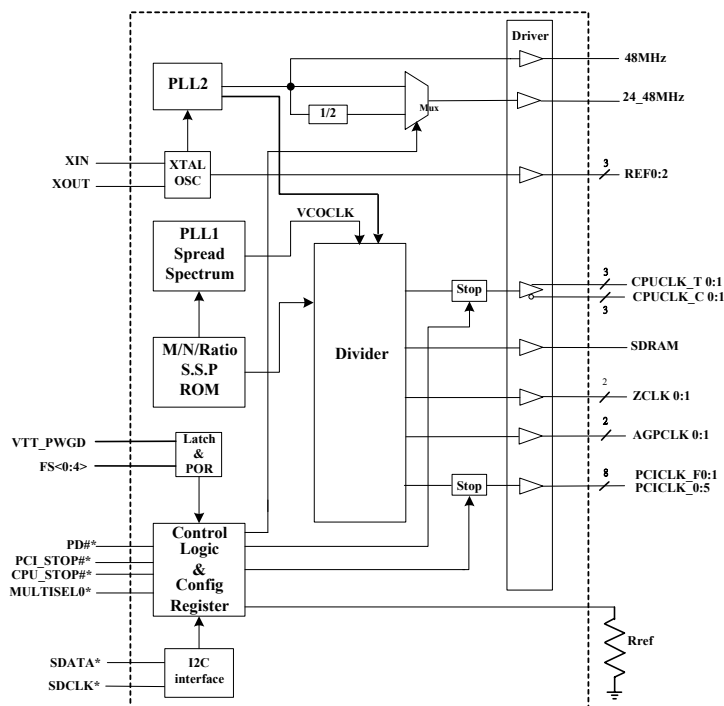
VDDR	1	48	VDDSD
FS0&/REF0	2	47	SDRAM
FS1&/REF1	3	46	GND
FS2&/REF2	4	45	CPU_STOP#*
GND	5	44	CPUCLKT_1
XIN	6	43	CPUCLKC_1
XOUT	7	42	VDDC
GND	8	41	GND
ZCLK0	9	40	CPUCLKT_0
ZCLK1	10	39	CPUCLKC_0
VDDZ	11	38	IREF
PCI_STOP#*	12	37	GND
VDDPCI	13	36	VDDA
FS3&/PCICLK_F0	14	35	SDCLK*
FS4&/PCICLK_F1	15	34	SDATA*
PCICLK0	16	33	PD#*/VTT_PWGD
PCICLK1	17	32	GND
GND	18	31	AGPCLK0
VDDPCI	19	30	AGPCLK1
PCICLK2	20	29	VDDAGP
PCICLK3	21	28	VDD48
PCICLK4	22	27	48MHz
PCICLK5	23	26	24_48MHz/MULTISEL0*
GND	24	25	GND

#: Active low

*: Internal pull up resistor 120K to VDD

&: Internal Pull-down resistor 120K to GND

4. BLOCK DIAGRAM





5. PIN DESCRIPTION

BUFFER TYPE SYMBOL	DESCRIPTION
IN	Input
IN _{tp120k}	Latched input at power up, internal 120KΩ pull up.
IN _{td120k}	Latched input at power up, internal 120KΩ pull down.
OUT	Output
OD	Open Drain
I/O	Bi-directional Pin
I/OD	Bi-directional Pin, Open Drain.
#	Active Low
*	Internal 120kΩ pull-up
&	Internal 120 kΩ pull-down

5.1 Crystal I/O

PIN	PIN NAME	TYPE	DESCRIPTION
6	XIN	IN	Crystal input with internal loading capacitors (18pF) and feedback resistors.
7	XOUT	OUT	Crystal output at 14.318 MHz nominally with internal loading capacitors (18pF).

5.2 CPU, ZCLK, SDRAM, PCI Clock Outputs

PIN	PIN NAME	TYPE	DESCRIPTION
40, 39, 44, 43	CPUCLKT_0 CPUCLKC_0, CPUCLKT_1 CPUCLKC_1,	OUT	True CPU clock output and Complementary CPU clock output. These pins will be stopped by CPU_STOP#
47	SDRAM	OUT	SDRAM clock output, which have syn. or asyn. Frequencies as CPU clocks. The clock phase is the same as CPUCLKT_0 and CPUCLKT_1.
14	PCICLK_F0	OUT	PCI free running clock during normal operation.
	FS3&	IN _{td120k}	Latched input for FS3 at initial power up for H/W selecting the output frequency. Internal 120KΩ pull-down
15	PCICLK_F1	OUT	PCI free running clock during normal operation.
	FS4&	IN _{td120k}	Latched input for FS4 at initial power up for H/W selecting the output frequency. Internal 120KΩ pull-down
16, 17, 20, 21, 22, 23	PCICLK [0:5]	OUT	Low skew (< 500 pS) PCI clock outputs.
31, 30	AGPCLK [0:1]	OUT	AGP clock outputs for AGP.
9, 10	ZCLK [0:1]	OUT	Z clock outputs for chipset.

5.3 I2C Control Interface

PIN	PIN NAME	TYPE	DESCRIPTION
34	SDATA*	I/O	Serial data of I ² C 2-wire control interface, Internal 120KΩ pull-up.
35	SDCLK*	IN	Serial clock of I ² C 2-wire control interface, Internal 120KΩ pull-up.

5.4 Fixed Frequency Outputs

PIN	PIN NAME	TYPE	DESCRIPTION
38	IREF	IN	Deciding the reference current for the CPUCLK pairs. The pin was connected to the precision resistor tied to ground to decide the appropriate current. There are two modes to select different current via power on trapping the Pin 26 (MULTISEL0). The table is show as follows.
2	REF0	OUT	3.3V, 14.318 MHz reference clock output.
	FS0 ^{&}	IN _{td120k}	Latched input for FS0 at initial power up for H/W selecting the output frequency. Internal 120 KΩ pull- down.
3	REF1	OUT	3.3V, 14.318 MHz reference clock output.
	FS1 ^{&}	IN _{td120k}	Latched input for FS1 at initial power up for H/W selecting the output frequency, Internal 120 KΩ pull- down.
4	REF2	OUT	3.3V, 14.318 MHz reference clock output.
	FS2 ^{&}	IN _{td120k}	Latched input for FS2 at initial power up for H/W selecting the output frequency. Internal 120 KΩ pull- down.
26	24_48 MHz	OUT	24 MHz or 48 MHz clock output selected by Register.
	MULTISEL0*	IN _{tp120k}	MULTISEL0* at initial power up for H/W selecting the current multiplier for CPU outputs. Internal 120 KΩ pull-up.
27	48 MHz	OUT	48 MHz output for USB.

5.5 Power Management Pins

PIN	PIN NAME	TYPE	DESCRIPTION
33	PD#*	IN	Power Down pin, low active all clocks are stopped, internal 120KΩ pull up.
	VTT_PWGD	IN	Power good input signal comes from ACPI with high active. This 3.3V input is level sensitive strobe used to determine FS [4:0] and MULTISEL0 input are valid and is ready to sample. This pin is high active.
45	CPU_STOP#*	IN	CPU clock stop control pin, This pin is low active. Internal 120KΩ pull-up.
12	PCI_STOP#*	IN	PCI clock stop control pin, This pin is low active. Internal 120KΩ pull-up.

5.6 Power Pins

PIN	PIN NAME	DESCRIPTION
1	VDDR	Power supply for REF0: 2 3.3V.
11	VDDZ	Power supply for ZCLK 3.3V.
36	VDDA	Power supply for core logic. 3.3V
42	VDDC	Power supply for CPUCLK 3.3V.
29	VDDAGP	Power supply for AGP outputs.
13,19	VDDPCI	Power supply for PCI outputs.
48	VDDSD	Power supply for SDRAM 3.3V.
28	VDD48	Power supply for 48/24 MHz outputs.
5, 8, 18, 24, 25, 32, 37, 41, 46	GND	Circuit Ground.

5.7 Hardware MULTSEL0 Selects Function

MULTSEL0 PIN 26	BOARD TARGET TRACE/TERM Z	REFERENCE R, IREF = VDD/(3*RR)	OUTPUT CURRENT	VOH @ Z
0	50 Ω	Rr = 221 1% IREF = 5.00 mA	Ioh = 4*IREF	1.0V @ 50
0	60 Ω	Rr = 221 1% IREF = 5.00 mA	Ioh = 4*IREF	1.2V @ 60
1	50 Ω	Rr = 221 1% IREF = 5.00 mA	Ioh = 6*IREF	1.5V @ 50
1	60 Ω	Rr = 221 1% IREF = 5.00 mA	Ioh = 6*IREF	1.8V @ 60
0	50 Ω	Rr = 475 1% IREF = 2.32 mA	Ioh = 4*IREF	0.47V @ 50
0	60 Ω	Rr = 475 1% IREF = 2.32 mA	Ioh = 4*IREF	0.56V @ 60
1	50 Ω	Rr = 475 1% IREF = 2.32 mA	Ioh = 6*IREF	0.7V @ 50
1	60 Ω	Rr = 475 1% IREF = 2.32 mA	Ioh = 6*IREF	0.84V @ 60

6. FREQUENCY SELECTION BY HARDWARE OR SOFTWARE

This frequency table is used at power on latched FS [4:0] value or software programming at SSEL [4:0] (Register 4 bit 4 ~ 7, 2)

FS4	FS3	FS2	FS1	FS0	CPU (MHz)	SDRAM (MHz)	ZCLK (MHz)	AGP (MHz)	PCI (MHz)
0	0	0	0	0	100.2	100.2	80.2	66.8	33.4
0	0	0	0	1	100.2	133.6	80.2	66.8	33.4
0	0	0	1	0	100.2	200.5	80.2	66.8	33.4
0	0	0	1	1	100.2	167.0	83.5	62.6	31.3
0	0	1	0	0	133.6	100.2	80.2	66.8	33.4
0	0	1	0	1	133.6	133.6	80.2	66.8	33.4
0	0	1	1	0	133.6	200.5	80.2	66.8	33.4
0	0	1	1	1	133.7	167.2	83.6	66.9	33.4
0	1	0	0	0	166.6	99.9	83.3	62.5	31.2
0	1	0	0	1	166.8	133.4	83.4	66.7	33.4
0	1	0	1	0	166.8	222.4	83.4	66.7	33.4
0	1	0	1	1	166.8	166.8	83.4	66.7	33.4
0	1	1	0	0	199.7	99.9	79.9	66.6	33.3
0	1	1	0	1	199.7	133.2	79.9	66.6	33.3
0	1	1	1	0	199.7	199.7	79.9	66.6	33.3
0	1	1	1	1	200.0	150.0	75.0	66.7	33.3
1	0	0	0	0	100.2	100.2	133.6	66.8	33.4
1	0	0	0	1	100.2	133.6	133.6	66.8	33.4
1	0	0	1	0	100.2	200.5	133.6	66.8	33.4
1	0	0	1	1	100.2	167.0	125.3	62.6	31.3
1	0	1	0	0	133.6	100.2	133.6	66.8	33.4
1	0	1	0	1	133.6	133.6	133.6	66.8	33.4
1	0	1	1	0	133.6	200.5	133.6	66.8	33.4
1	0	1	1	1	133.7	167.2	133.7	66.9	33.4
1	1	0	0	0	166.6	99.9	124.9	62.5	31.2
1	1	0	0	1	166.8	133.4	133.4	66.7	33.4
1	1	0	1	0	166.8	222.4	133.4	66.7	33.4
1	1	0	1	1	166.8	166.8	133.4	66.7	33.4
1	1	1	0	0	199.7	99.9	133.2	66.6	33.3
1	1	1	0	1	199.7	133.2	133.2	66.6	33.3
1	1	1	1	0	199.7	199.7	133.2	66.6	33.3
1	1	1	1	1	200.0	150.0	120.0	66.7	33.3



7. I²C CONTROL AND STATUS REGISTERS

The Register 0~3 are reserved for external clock buffer

(The register No. Is increased by 1 if use byte data read/write protocol)

7.1 Register 4: Frequency Select (Default = 00H)

BIT	NAME	PWD	DESCRIPTION
7	SSEL [3]	0	Frequency selection by software via I ² C
6	SSEL [2]	0	
5	SSEL [1]	0	
4	SSEL [0]	0	
3	EN_SSEL	0	Enable software program FS [4:0]. 0 = Select frequency by hardware. 1 = Select frequency by software I ² C - Bit 4:7, 2.
2	SSEL [4]	0	Frequency selection bit 4
1	EN_SPSP	0	Enable Spread Spectrum in the frequency table. 0 = Normal 1 = Spread Spectrum enabled
0	EN_SAFE_FREQ	0	Enable reload safe frequency when the watchdog is timeout. 0 = reload the FS [4:0] latched pins when watchdog time out. 1 = reload the safe frequency bit defined at Register 9 bit 4~0.

7.2 Register 5: CPU, SDRAM Clock (1 = Enable, 0 = Stopped) (Default = FFH)

BIT	PIN NO	PWD	DESCRIPTION
7	47	1	SDRAM output control
6	44, 43	1	CPUCLKT/C1 output control
5	40, 39	1	CPUCLKT/C0 output control
4	15	X	Invert Power on latched value of FS4 pin, Default 1 (Read only)
3	14	X	Invert Power on latched value of FS3 pin. Default 1 (Read only)
2	4	X	Invert Power on latched value of FS2 pin. Default 1 (Read only)
1	3	X	Invert Power on latched value of FS1 pin. Default 1 (Read only)
0	2	X	Invert Power on latched value of FS0 pin. Default 1 (Read only)

7.3 Register 6 PCI Clock (1 = Enable, 0 = Stopped) (Default = FFH)

BIT	PIN NO	PWD	DESCRIPTION
7	15	1	PCICLK_F1 output control
6	14	1	PCICLK_F0 output control
5	23	1	PCICLK 5 output control
4	22	1	PCICLK 4 output control
3	21	1	PCICLK 3 output control
2	20	1	PCICLK 2 output control
1	17	1	PCICLK 1 output control
0	16	1	PCICLK 0 output control

7.4 Register 7 48 MHz, ZCLK, REF Clock (1 = Enable, 0 = Stopped) (Default = FFH)

BIT	PIN NO	PWD	DESCRIPTION
7	27	1	48 MHZ output control
6	26	1	24_48 MHz output control
5	SEL_24	1	24/48 MHz frequency control 1: 24 MHz. 0: 48 MHz.
4	10	1	ZCLK1 output control
3	9	1	ZCLK0 output control
2	4	1	REF2 output control
1	3	1	REF1 output control
0	2	1	REF0 output control

7.5 Register 8: AGP Control (1 = Enable, 0 = Stopped) (Default = CEH)

BIT	Pin NO	PWD	DESCRIPTION
7		1	CPUCLKT/C0 Stop control: 0: CPUCLK0 free run 1: CPUCLK0 can stopped by CPU_STOP#
6		1	CPUCLKT/C1 Stop control: 0: CPUCLK1 free run 1: CPUCLK1 can stopped by CPU_STOP#
5		0	PCI_F0 Stop control: 0: PCI_F0 free run 1: PCI_F0 can stopped by PCI_STOP#
4		0	PCI_F1 Stop control: 0: PCI_F1 free run 1: PCI_F1 can stopped by PCI_STOP#
3	30	1	AGP_1 output control
2	31	1	AGP_0 output control
1	MULTISEL0	X	MULTISEL0 trapping pin data read back, Default 1.
0	Reserved	0	Reserved



7.6 Register 9: Watchdog Control (Default = 00H)

BIT	NAME	PWD	DESCRIPTION
7	Reserved	0	Reserved
6	EN_WD	0	Enable Watchdog Timer if set to 1. Set to 0, disable watchdog timer. Read this bit will return a counting state. If timer continues down count, this bit will return 1. Otherwise, this bit will return 0.
5	WD_TIMEOUT	0	Watchdog Timeout Status. If the watchdog is started and timer down counts to zero, this bit will be set to 1. Clear this bit to logic 0, If set to 1, when the watchdog is restart in the next time. This bit is Read Only.
4	SAF_FREQ [4]	0	Watchdog safe frequency bits. These bits will be reloaded into FS [4:0], if the watchdog is timeout and enable reload safe frequency bits.
3	SAF_FREQ [3]	0	
2	SAF_FREQ [2]	0	
1	SAF_FREQ [1]	0	
0	SAF_FREQ [0]	0	

7.7 Register 10: Watchdog Timer (Default = 08H)

BIT	NAME	PWD	DESCRIPTION
7	WD_TIME [7]	0	Watchdog timeout time. The bit resolution is 250 mS. The default time is 8*250 mS = 2.0 seconds. If the watchdog timer is start, this register will be down count. Read this register will return a down count value.
6	WD_TIME [6]	0	
5	WD_TIME [5]	0	
4	WD_TIME [4]	0	
3	WD_TIME [3]	1	
2	WD_TIME [2]	0	
1	WD_TIME [1]	0	
0	WD_TIME [0]	0	

7.8 Register 11: M/N Program (Default = ABH)

BIT	NAME	PWD	DESCRIPTION
7	N_DIV [8]	1	Programmable N divisor value. Bit 7 ~0 are defined in the Register 12.
6	TEST2	0	Test bit 2. WINBOND test bit, do not change them.
5	TEST1	1	Test bit 1. WINBOND test bit, do not change them.
4	M_DIV [4]	0	Programmable M divisor value.
3	M_DIV [3]	1	
2	M_DIV [2]	0	
1	M_DIV [1]	1	
0	M_DIV [0]	1	

7.9 Register 12: M/N Program (Default = 2FH)

BIT	NAME	PWD	DESCRIPTION
7	N_DIV [7]	0	Programmable N divisor value bit 7 ~0. The bit 8 is defined in Register 11.
6	N_DIV [6]	0	
5	N_DIV [5]	1	
4	N_DIV [4]	0	
3	N_DIV [3]	1	
2	N_DIV [2]	1	
1	N_DIV [1]	1	
0	N_DIV [0]	1	

7.10 Register 13: Spread Spectrum Programming (Default = 1FH)

BIT	NAME	PWD	DESCRIPTION
7	SP_UP [3]	0	Spread Spectrum Up Counter bit 3.
6	SP_UP [2]	0	Spread Spectrum Up Counter bit 2.
5	SP_UP [1]	0	Spread Spectrum Up Counter bit 1.
4	SP_UP [0]	1	Spread Spectrum Up Counter bit 0
3	SP_DOWN [3]	1	Spread Spectrum Down Counter bit 3
2	SP_DOWN [2]	1	Spread Spectrum Down Counter bit 2
1	SP_DOWN [1]	1	Spread Spectrum Down Counter bit 1
0	SP_DOWN [0]	1	Spread Spectrum Down Counter bit 0

7.11 Register 14: Divisor and Step-less Enable Control (Default = 4CH)

BIT	NAME	PWD	DESCRIPTION
7	EN_MN_PROG	0	0: use frequency table 1: use M/N register to program frequency The equation is VCO freq. = 14.318 MHz * (N+4)/ M. When the watchdog timer is timeout, this will be clear. In this time, the frequency is set to hardware default latched or safe frequency set by EN_SFAE_FREQ (Register 4 bit 0).
6	RATIO_SEL [4]	1	CPU, PCI, AGP, SDRAM, and ZCLK ratio selection. The ratio is shown as following table.
5	RATIO_SEL [3]	0	
4	RATIO_SEL [2]	0	
3	RATIO_SEL [1]	1	
2	RATIO_SEL [0]	1	Test bit 0. WINBOND test bit, do not change them.
1	TEST0	0	
0	Reserved	0	



7.12 Register 15: CPU_ZCLK Skew Control (Default = A7H)

BIT	NAME	PWD	DESCRIPTION
7	CPU_ZCLK_SKEW [2]	1	CPU to ZCLK SKEW control
6	Reserved	0	Reserved
5	Reserved	1	Reserved
4	Reserved	0	
3	Reserved	0	
2	Reserved	1	
1	Reserved	1	
0	Reserved	1	

7.13 Register 16: CPU_AGP_SKEW (Default = 1CH)

BIT	NAME	PWD	DESCRIPTION
7	SEL [1]	0	AGP & PCI FIX frequency (PCI = AGP/2) SEL [1:0] for AGP 00: 72 MHZ 01: 64 MHZ 10: 77MHZ 11: 67MHZ
6	SEL [0]	0	
5	FIX_AGP_PCI	0	0:normal mode, 1: fix mode
4	CPU_STOP	1	CPU_STOP pin read back
3	PCI_STOP	1	CPU_STOP pin read back
2	CPU_AGP_SKEW [2]	1	CPU to AGP skew.
1	CPU_AGP_SKEW [1]	0	
0	CPU_AGP_SKEW [0]	0	

7.14 Register 17: Skew Control (Default = 24H)

BIT	NAME	PWD	DESCRIPTION
7	CPU_ZCLK_SKEW [1]	0	CPU to AGP skew
6	CPU_ZCLK_SKEW [0]	0	
5	CPU_SDRAM_SKEW [2]	1	CPU to SDRAM skew
4	CPU_SDRAM_SKEW [1]	0	
3	CPU_SDRAM_SKEW [0]	0	
2	CPU_PCI_SKEW [2]	1	CPU to PCI skew
1	CPU_PCI_SKEW [1]	0	
0	CPU_PCI_SKEW [0]	0	

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7.15 Register 18: Winbond Chip ID (Read Only) (Default = 77H)

BIT	NAME	PWD	DESCRIPTION
7	CHPI_ID [7]	0	WINBOND Chip ID. W83194BR-648 is 0x77.
6	CHPI_ID [6]	1	WINBOND Chip ID.
5	CHPI_ID [5]	1	WINBOND Chip ID.
4	CHPI_ID [4]	1	WINBOND Chip ID.
3	CHPI_ID [3]	0	WINBOND Chip ID.
2	CHPI_ID [2]	1	WINBOND Chip ID.
1	CHPI_ID [1]	1	WINBOND Chip ID.
0	CHPI_ID [0]	1	WINBOND Chip ID.

7.16 Register 19: Winbond Chip ID (Read Only) (Default = 11H)

BIT	NAME	PWD	DESCRIPTION
7	SUB_ID [3]	0	WINBOND Sub-Chip ID. The sub-chip ID of W83194BR-648 is defined as 0001b.
6	SUB_ID [2]	0	WINBOND Sub-Chip ID.
5	SUB_ID [1]	0	WINBOND Sub-Chip ID.
4	SUB_ID [0]	1	WINBOND Sub-Chip ID.
3	VER_ID [3]	0	WINBOND Version ID. The Version ID of W83194BR-648 is 0001b.
2	VER_ID [2]	0	WINBOND Version ID.
1	VER_ID [1]	0	WINBOND Version ID.
0	VER_ID [0]	1	WINBOND Version ID.



7.17 Ratio Selection Table

Table of CPU, PCI, AGP, SDRAM, and ZCLK clock selection.

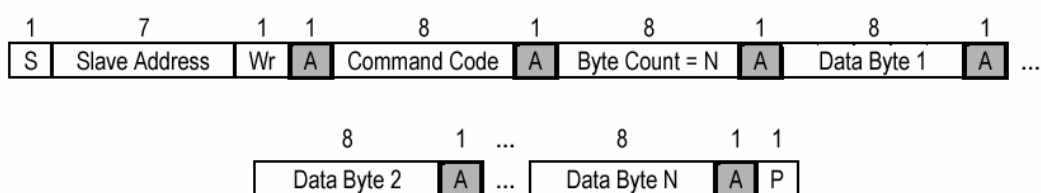
Reg14 Bit6	Reg14 Bit5	Reg14 Bit4	Reg14 Bit3	Reg14 Bit2	CPU	SDRAM	ZCLK	AGP	PCI
SSEL4	SSEL3	SSEL2	SSEL1	SSEL0	Ratio	Ratio	Ratio	Ratio	Ratio
0	0	0	0	0	4	4	5	6	12
0	0	0	0	1	4	3	5	6	12
0	0	0	1	0	4	2	5	6	12
0	0	0	1	1	5	3	6	8	16
0	0	1	0	0	3	4	5	6	12
0	0	1	0	1	3	3	5	6	12
0	0	1	1	0	3	2	5	6	12
0	0	1	1	1	5	4	8	10	20
0	1	0	0	0	3	5	6	8	16
0	1	0	0	1	4	5	8	10	20
0	1	0	1	0	4	3	8	10	20
0	1	0	1	1	4	4	8	10	20
0	1	1	0	0	2	4	5	6	12
0	1	1	0	1	2	3	5	6	12
0	1	1	1	0	2	2	5	6	12
0	1	1	1	1	3	4	8	9	18
1	0	0	0	0	4	4	3	6	12
1	0	0	0	1	4	3	3	6	12
1	0	0	1	0	4	2	3	6	12
1	0	0	1	1	5	3	4	8	16
1	0	1	0	0	3	4	3	6	12
1	0	1	0	1	3	3	3	6	12
1	0	1	1	0	3	2	3	6	12
1	0	1	1	1	5	4	5	10	20
1	1	0	0	0	3	5	4	8	16
1	1	0	0	1	4	5	5	10	20
1	1	0	1	0	4	3	5	10	20
1	1	0	1	1	4	4	5	10	20
1	1	1	0	0	2	4	3	6	12
1	1	1	0	1	2	3	3	6	12
1	1	1	1	0	2	2	3	6	12
1	1	1	1	1	3	4	5	9	18

8. ACCESS INTERFACE

The W83194BR-648 provides I²C Serial Bus for microprocessor to read/write internal registers. In the W83194BR-648 is provided Block Read/Block Write and Byte-Data Read/Write protocol. The I²C address is defined at 0xD2.

Block Read and Block Write Protocol

8.1 Block Write Protocol

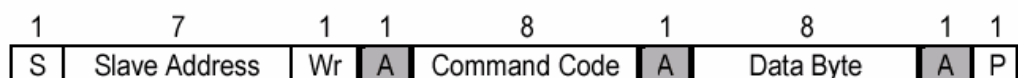


8.2 Block Read Protocol

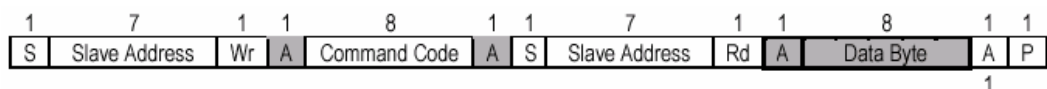


In block mode, the command code must filled 8'h00

8.3 Byte Write Protocol



8.4 Byte Read Protocol





9. SPECIFICATIONS

9.1 Absolute Maximum Ratings

Stresses greater than those listed in this table may cause permanent damage to the device. Precautions should be taken to avoid application of any voltage higher than the maximum rated voltages to this circuit. Subjection to maximum conditions for extended periods may affect reliability. Unused inputs must always be tied to an appropriate logic voltage level (Ground or VDD).

PARAMETER	RATING
Absolute 3.3V Core Supply Voltage	-0.5V to +4.6V
Absolute 3.3V I/O Supply Voltage	-0.5 V to +4.6 V
Operating 3.3V Core Supply Voltage	3.135V to 3.465V
Operating 3.3V I/O Supply Voltage	3.135V to 3.465V
Storage Temperature	-65°C to +150°C
Ambient Temperature	-55°C to +125°C
Operating Temperature	0°C to +70°C
Input ESD Protection (Human body model)	2000V

9.2 General Operating Characteristics

VDDR = VDDZ = VDDA = VDDC = VDDAGP = VDDPCI = VDDSD = VDD48 = 3.3V $\pm$ 5 %, TA = 0°C to +70°C, CI = 10pF

PARAMETER	SYM.	MIN.	MAX.	UNITS	TEST CONDITIONS
Input Low Voltage	V _{IL}		0.8	V _{dc}	
Input High Voltage	V _{IH}	2.0		V _{dc}	
Output Low Voltage	V _{OL}		0.4	V _{dc}	All outputs using 3.3V power
Output High Voltage	V _{OH}	2.4		V _{dc}	All outputs using 3.3V power
Dynamic Supply Current	I _{dd}		350	mA	CPU = 100 to 200 MHz PCI = 33.3 MHz with load
Input Pin Capacitance	C _{in}		5	pF	
Output Pin Capacitance	C _{out}		6	pF	
Input Pin Inductance	L _{in}		7	nH	



9.3 Skew Group Timing Clock

VDDR = VDDZ = VDDA = VDDC = VDDAGP = VDDPCI = VDDSD = VDD48 = 3.3V $\pm$ 5 %, TA = 0°C to +70°C, CI = 10pF

PARAMETER	MIN.	TYP.	MAX.	UNITS	TEST CONDITIONS
CPU to SDRAM Skew	-2	0	2	nS	CPU Crossing point to SDRAM at 1.5V
CPU (early) to AGP Skew	1	2	4	nS	CPU Crossing point to AGP at 1.5V
CPU (early) to ZCLK Skew	1	2	4	nS	CPU Crossing point to ZCLK at 1.5V
CPU (early) to PCI Skew	1	2	4	nS	CPU Crossing point to PCI at 1.5V
CPU to CPU Skew			150	pS	Crossing point
AGP to AGP Skew			175	pS	Measured at 1.5V
ZCLK to ZCLK Skew			175	pS	Measured at 1.5V
PCI to PCI Skew			500	pS	Measured at 1.5V
48 MHz to 48 MHz Skew			1000	pS	Measured at 1.5V
REF to REF Skew			500	pS	Measured at 1.5V

9.4 CPU 0.7V Electrical Characteristics

VDDA = VDDC = 3.3V $\pm$ 5 %, TA = 0°C to +70°C, Test load Rs = 33, Rp = 49.9 CI = 10pF, Vol = 0.14V, Voh = 0.56V, Vr = 475, IRE = 2.32mA, Ioh = 6*IREF

PARAMETER	MIN.	MAX.	UNITS	TEST CONDITIONS
Rise Time	175	700	pS	100 to 200 MHz
Fall Time	175	700	pS	100 to 200 MHz
Absolute Crossing Point Voltages	250	550	mV	100 to 200 MHz
Cycle to Cycle jitter		125	pS	100 to 200 MHz
Duty Cycle	45	55	%	100 to 200 MHz

9.5 CPU 1.0V Electrical Characteristics

VDDA = VDDC = 3.3V $\pm$ 5 %, TA = 0°C to +70°C, Test load Rs = 33, Rp = 49.9 CI = 10pF, Vol = 0.2V, Voh = 0.8V, Vr = 221, IREF = 5.0 mA, Ioh = 4*IREF

PARAMETER	MIN.	MAX.	UNITS	TEST CONDITIONS
Rise Time	300	600	pS	100 to 200 MHz
Fall Time	300	600	pS	100 to 200 MHz
Absolute Crossing Point Voltages	510	760	mV	100 to 200 MHz
Cycle to Cycle Jitter		200	pS	100 to 200 MHz
Duty Cycle	45	55	%	100 to 200 MHz



9.6 AGP Electrical Characteristics

VDDAGP = 3.3V $\pm$ 5 %, TA = 0°C to +70°C, Test load, C = 10pF,

PARAMETER	MIN.	MAX.	UNITS	TEST CONDITIONS
Rise Time	500	1600	pS	Measure from 0.4V to 2.4V
Fall Time	500	1600	pS	Measure from 2.4V to 0.4V
Cycle to Cycle Jitter		250	pS	Measure 1.5V point
Duty Cycle	45	55	%	
Pull-Up Current Min.	-33		mA	Vout = 1.0V
Pull-Up Current Max.		-33	mA	Vout = 3.135V
Pull-Down Current Min.	30		mA	Vout = 1.95V
Pull-Down Current Max.		38	mA	Vout = 0.4V

9.7 PCI Electrical Characteristics

VDDPCI = 3.3V $\pm$ 5 %, TA = 0°C to +70°C, Test load, CI = 10pF

PARAMETER	MIN.	MAX.	UNITS	TEST CONDITIONS
Rise Time	500	2000	pS	Measure from 0.4V to 2.4V
Fall Time	500	2000	pS	Measure from 2.4V to 0.4V
Cycle to Cycle Jitter		500	pS	Measure 1.5V point
Duty Cycle	45	55	%	
Pull-Up Current Min.	-33		mA	Vout = 1.0V
Pull-Up Current Max.		-33	mA	Vout = 3.135V
Pull-Down Current Min.	30		mA	Vout = 1.95V
Pull-Down Current Max.		38	mA	Vout = 0.4V

9.8 ZCLK Electrical Characteristics

VDDZ = 3.3V $\pm$ 5 %, TA = 0°C to +70°C, Test load, CI = 10pF

PARAMETER	MIN.	MAX.	UNITS	TEST CONDITIONS
Rise Time	500	1600	pS	Measure from 0.4V to 2.4V
Fall Time	500	1600	pS	Measure from 2.4V to 0.4V
Cycle to Cycle Jitter		250	pS	Measure 1.5V point
Duty Cycle	45	55	%	
Pull-Up Current Min.	-33		mA	Vout = 1.0V
Pull-Up Current Max.		-33	mA	Vout = 3.135V
Pull-Down Current Min.	30		mA	Vout = 1.95V
Pull-Down Current Max.		38	mA	Vout = 0.4V



9.9 SDRAM Electrical Characteristics

VDDSD = 3.3V $\pm$ 5 %, TA = 0°C to +70°C, Test load, Cl = 10pF

PARAMETER	MIN.	MAX.	UNITS	TEST CONDITIONS
Rise Time	500	1600	pS	Measure from 0.4V to 2.4V
Fall Time	500	1600	pS	Measure from 2.4V to 0.4V
Cycle to Cycle Jitter		250	pS	Measure 1.5V point
Duty Cycle	45	55	%	
Pull-Up Current Min.	-33		mA	Vout = 1.0V
Pull-Up Current Max.		-33	mA	Vout = 3.135V
Pull-Down Current Min.	30		mA	Vout = 1.95V
Pull-Down Current Max.		38	mA	Vout = 0.4V

9.10 24M, 48M Electrical Characteristics

VDD48 = 3.3V $\pm$ 5 %, TA = 0°C to +70°C, Test load, Cl = 10pF

PARAMETER	MIN.	MAX.	UNITS	TEST CONDITIONS
Rise Time	1000	4000	pS	Measure from 0.4V to 2.4V
Fall Time	1000	4000	pS	Measure from 2.4V to 0.4V
Long Term Jitter		500	pS	Measure 1.5V point
Duty Cycle	45	55	%	
Pull-Up Current Min.	-29		mA	Vout = 1.0V
Pull-Up Current Max.		-23	mA	Vout = 3.135V
Pull-Down Current Min.	29		mA	Vout = 1.95V
Pull-Down Current Max.		27	mA	Vout = 0.4V

9.11 REF Electrical Characteristics

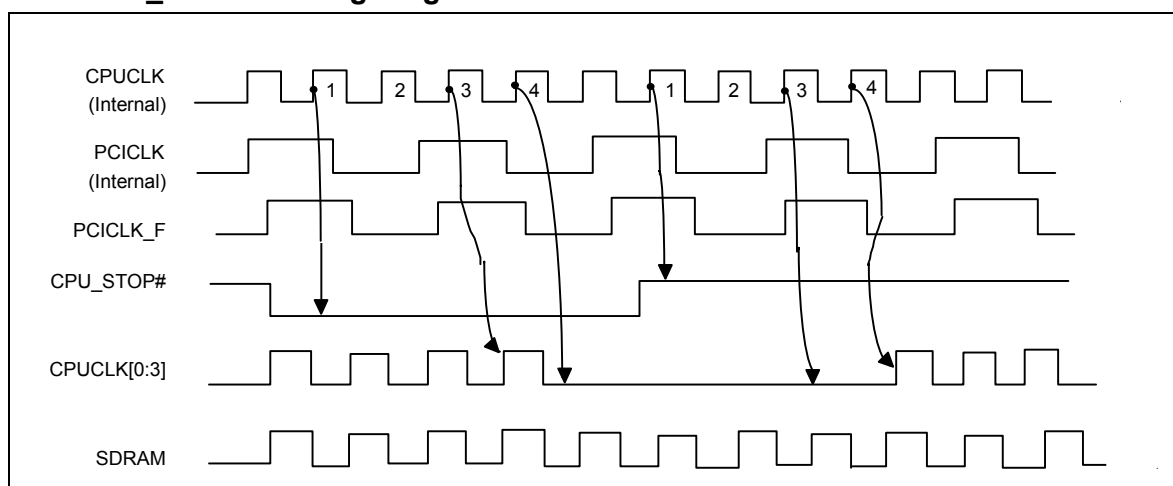
VDD48 = 3.3V $\pm$ 5 %, TA = 0°C to +70°C, Test load, Cl = 10pF

PARAMETER	MIN.	MAX.	UNITS	TEST CONDITIONS
Rise Time	1000	4000	ps	Measure from 0.4V to 2.4V
Fall Time	1000	4000	ps	Measure from 2.4V to 0.4V
Cycle to Cycle Jitter		1000	ps	Measure 1.5V point
Duty Cycle	45	55	%	
Pull-Up Current Min.	-33		mA	Vout=1.0V
Pull-Up Current Max.		-33	mA	Vout=3.135V
Pull-Down Current Min.	30		mA	Vout=1.95V
Pull-Down Current Max.		38	mA	Vout=0.4V



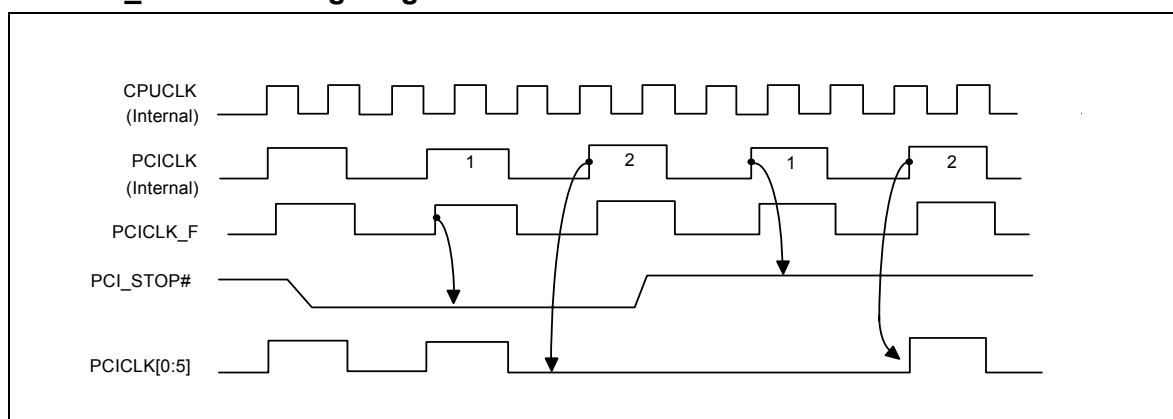
10. POWER MANAGEMENT TIMING

10.1 CPU_STOP# Timing Diagram



For synchronous Chipset, CPU_STOP# pin is an asynchronous “ active low ” input pin used to stop the CPU clocks for low power operation. This pin is asserted synchronously by the external control logic at the rising edge of free running PCI clock (PCICLK_F). All other clocks will continue to run while the CPU clocks are stopped. The CPU clocks will always be stopped in a low state and resume output with full pulse width. In this case, CPU “ locks on latency ” is less than 4 CPU clocks and “ locks off latency ” is less than 4 CPU clocks.

10.2 PCI_STOP# Timing Diagram



For synchronous Chipset, PCI_STOP# pin is an asynchronous Active low” input pin used to stop the PCICLK [0:4] for low power operation. This pin is asserted synchronously by the external control logic at the rising edge of free running PCI clock (PCICLK_F). All other clocks will continue to run while the PCI clocks are stopped. The PCI clocks will always be stopped in a low state and resume output with full pulse width. In this case, PCI “ locks on latency ” is less than 2 PCI clocks and “ locks off latency ” is less than 2 PCI clocks.

W83194BR-648

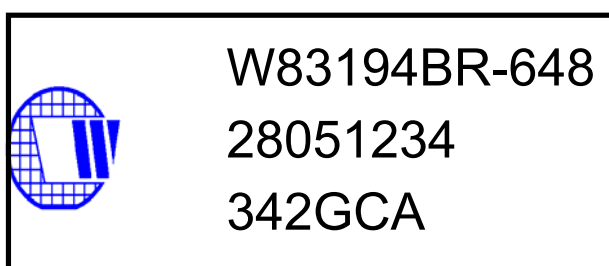


11. ORDERING INFORMATION

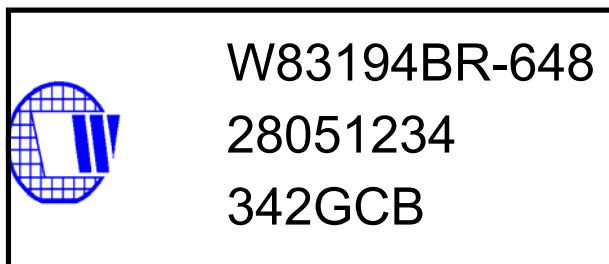
PART NUMBER	PACKAGE TYPE	PRODUCTION FLOW
W83194BR-648	48-pin SSOP	Commercial, 0°C to +70°C

12. HOW TO READ THE TOP MARKING

Version A



Version B



1st line: Winbond logo and the type number: W83194BR-648

2nd line: Tracking code 2 8051234

2: wafers manufactured in Winbond FAB 2

8051234: wafer production series lot number

3rd line: Tracking code 342 G C A

342: packages made in '2003, week 42

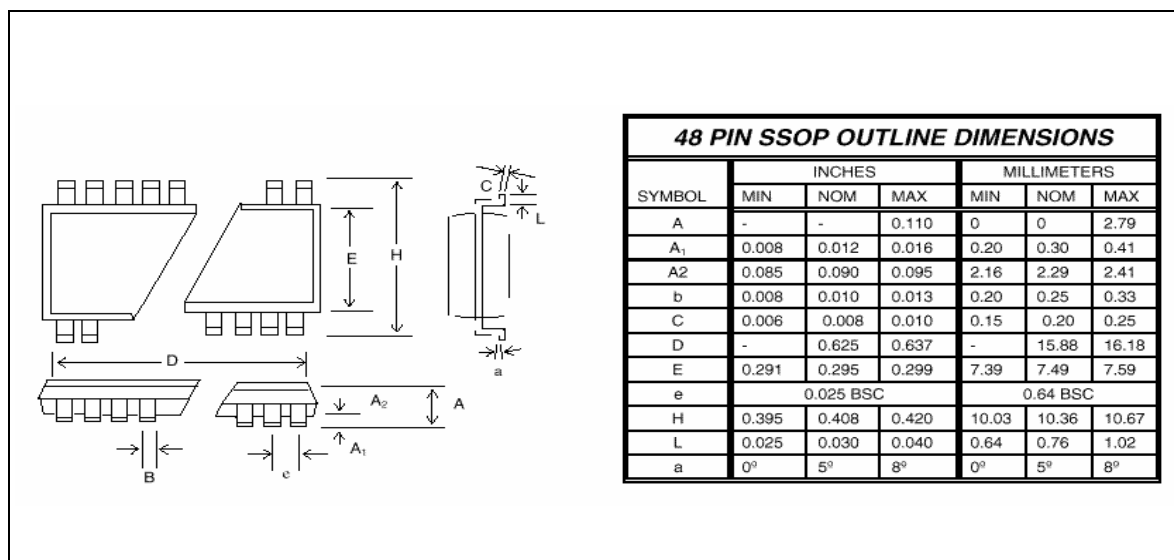
G: assembly house ID; O means OSE, G means GR

C: Internal use code

A: IC revision

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13. PACKAGE DRAWING AND DIMENSIONS



**14. REVISION HISTORY**

VERSION	DATE	PAGE	DESCRIPTION
		n.a.	All of the versions before 0.50 are for internal use.
0.5	02/7/03	17~22	Add AC/DC Specifications and Power management
0.6	2/21/03	All	Update new form
0.7	12/18/03	7~11, 19	Correction IC version, add register default value and correction some description and default value
1.0	05/06/04		Update on web
1.1	04/13/2005	22	Add disclaimer

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